



IEC 60194-2

Edition 1.0 2017-12

INTERNATIONAL STANDARD



**Printed boards design, manufacture and assembly – Vocabulary –
Part 2: Common usage in electronic technologies as well as printed board and
electronic assembly technologies**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS DESIGN, MANUFACTURE
AND ASSEMBLY – VOCABULARY –****Part 2: Common usage in electronic technologies as well
as printed board and electronic assembly technologies**

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International Standard IEC 60194-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This first edition, together with IEC 60194-1, will cancel and replace IEC 60194:2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to IEC 60194:2015:

- a) exclusion of 32 general terms better served by other TCs;
- b) exclusion of 47 terms no longer used by the electronics assembly industry;
- c) inclusion of 13 new terms related with device embedded substrate technology;
- d) removal of identification codes for terms as well as annexes.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1442/CDV	91/1473/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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